

## Heat Sink Compound - High Density 20g Syringe 10cc

### Product Highlights

- High Density Thermal Paste.
- White, non-curing and non-flowing thermally conductive heat sink compound.
- Heavily filled with heat-conductive metal oxide. Provides high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating ( $2 \times 10^{15}$  ohm-cm).



### Specifications

Viscosity:	542,000 cP (542,000 mPa·s)
Density:	2.1g/cc
Bleed:	0.23%
Thermal Conductivity:	0.67 W/m·K
Thermal Resistance:	0.16 °C*cm <sup>2</sup> /W
Electrical Volume Resistivity:	$2 \times 10^{15}$ ohm-cm
Dielectric Strength:	8.27 MV/m (210V/mil)
Evaporation:	0.38%
Size:	20g Syringe (10cc)

### Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an operating temperature of 20-25°C (68-77°F) before use.

### Shelf Life

>60 months

### Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Chip Quik® Thermal Paste Orderable Part Numbers

<b>Thermal Conductivity (W/m·K)</b>	<b>Thermal Resistance (°C·cm<sup>2</sup>/W)</b>	<b>Density (g/cc)</b>	<b>Color</b>	<b>Package</b>	<b>Size (g)</b>	<b>Orderable Part Number</b>
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G